

IN THE SPECIFICATION:

Please amend the first full paragraph appearing on page 2 as follows:

~~Cross Reference~~ Cross-Reference to Related Application: This application is a divisional of application Serial No. 09/223,059, filed December 30, 1998, ~~pending~~, now U.S. Patent 6,455,354, issued September 24, 2002.

Please amend the paragraph bridging pages 3 and 4 as follows:

An exemplary technique of forming the encapsulant 218 is molding and, more specifically, transfer molding. In the transfer molding process (and with specific reference to COB die assemblies), after the semiconductor die 202 is attached to the semiconductor substrate 206 (*e.g.*, FR-4 printed circuit board) and electrical connections made (by wire bonding or TAB) to form a die assembly, the die assembly is placed in a mold cavity in a transfer molding machine. The die assembly is thereafter encapsulated in a thermosetting polymer which, when heated, reacts irreversibly to form a highly ~~cross-linked~~ cross-linked matrix no longer capable of being re-melted. Additionally, another common manner of forming encapsulants for COB assemblages is "glob top" polymeric encapsulation. Glob top encapsulation can be applied by dispensing suitably degassed material from a reservoir through a needle-like nozzle onto the die assembly.

Please amend the second full paragraph on page 9 as follows:

One embodiment of the present invention comprises a semiconductor die assembly including a semiconductor substrate having an opening defined therethrough and a semiconductor die having a plurality of electrical connection areas, such as bond pads and hereinafter referred to as "~~bond pads~~", pads," on an active surface thereof. The semiconductor die is attached to the semiconductor substrate such that the bond pads are aligned with the semiconductor substrate opening. The semiconductor die is attached to the semiconductor substrate with an adhesive tape which preferably extends proximate an edge of the semiconductor die and proximate an edge of the semiconductor substrate opening. Such an

adhesive tape configuration maximizes the contact area between the semiconductor die and the semiconductor substrate. This increased contact area assists in preventing the semiconductor die from flexing, twisting, or bending away from the semiconductor substrate, thus reducing or eliminating localized stress failures occurring during subsequent molding processes.